

APT B1612SYKCGKC

SUPER BRIGHT YELLOW
GREEN

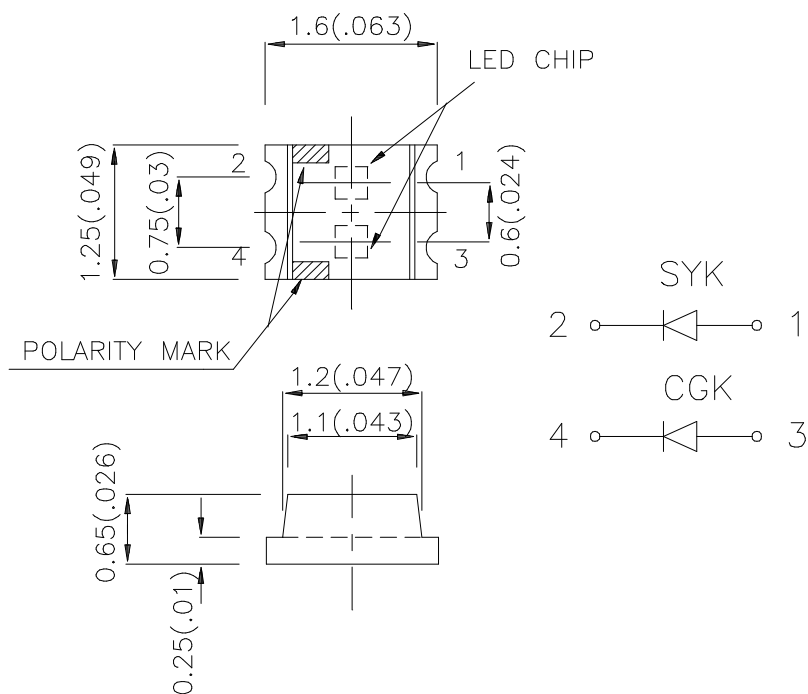
Features

- 1.6mmx1.25mm SMT LED, 0.65mm THICKNESS.
- BI-COLOR, LOW POWER CONSUMPTION.
- WIDE VIEWING ANGLE.
- IDEAL FOR BACKLIGHT AND INDICATOR.
- VARIOUS COLORS AND LENS TYPES AVAILABLE.
- PACKAGE : 2000PCS / REEL.

Description

The Super Bright Yellow source color devices are made with DH InGaAlP on GaAs substrate Light Emitting Diode. The Green source color devices are made with InGaAlP on GaAs substrate Light Emitting Diode.

Package Dimensions



Notes:

1. All dimensions are in millimeters (inches).
2. Tolerance is ± 0.2 (0.0079") unless otherwise noted.
3. Specifications are subject to change without notice.

Selection Guide

Part No.	Dice	Lens Type	Iv (mcd) @ 20 mA		Viewing Angle
			Min.	Typ.	2θ1/2
APT B1612SYKCGKC	SUPER BRIGHT YELLOW (InGaAlP)	WATER CLEAR	18	50	120°
	GREEN (InGaAlP)		18	50	

Note:

1. θ1/2 is the angle from optical centerline where the luminous intensity is 1/2 the optical centerline value.

Electrical / Optical Characteristics at T_A=25°C

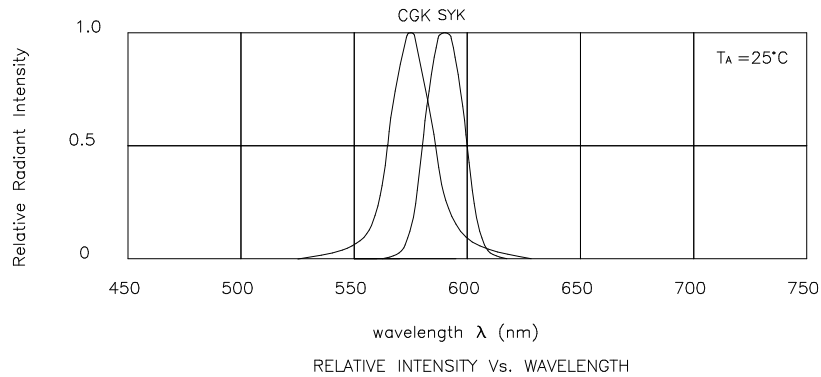
Symbol	Parameter	Device	Typ.	Max.	Units	Test Conditions
λ _{peak}	Peak Wavelength	Super Bright Yellow Green	590 574		nm	I _F =20mA
λ _D	Dominate Wavelength	Super Bright Yellow Green	590 570		nm	I _F =20mA
Δλ _{1/2}	Spectral Line Half-width	Super Bright Yellow Green	20 20		nm	I _F =20mA
C	Capacitance	Super Bright Yellow Green	20 15		pF	V _F =0V;f=1MHz
V _F	Forward Voltage	Super Bright Yellow Green	2.0 2.1	2.5 2.5	V	I _F =20mA
I _R	Reverse Current	All		10	uA	V _R = 5V

Absolute Maximum Ratings at T_A=25°C

Parameter	Super Bright Yellow	Green	Units
Power dissipation	125	105	mW
DC Forward Current	30	30	mA
Peak Forward Current [1]	175	150	mA
Reverse Voltage	5		V
Operating/Storage Temperature	-40°C To +85°C		

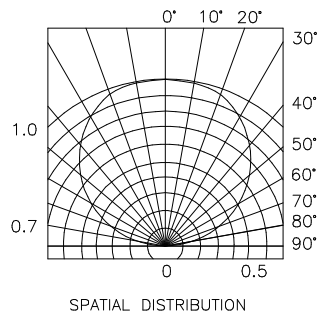
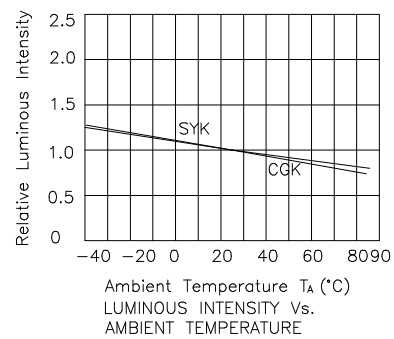
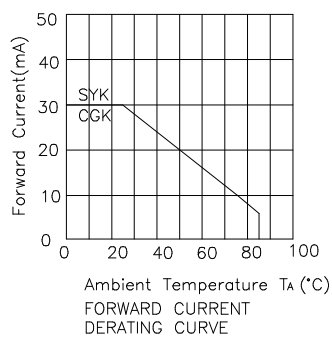
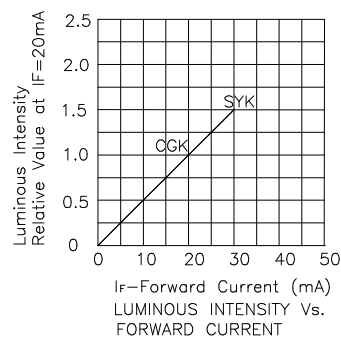
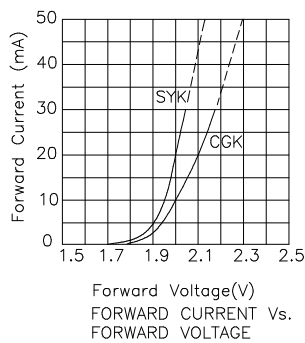
Note:

1. 1/10 Duty Cycle, 0.1ms Pulse Width.



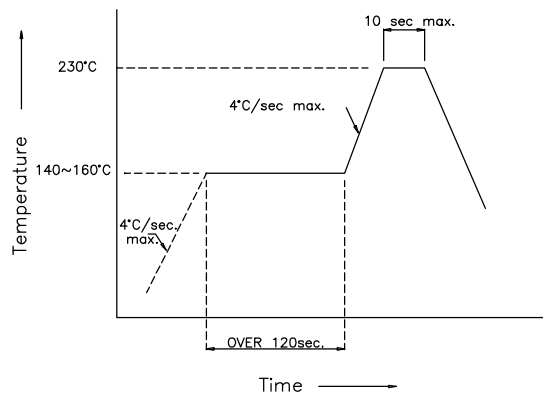
Super Bright Yellow/Green

APT B1612 SYK CGK

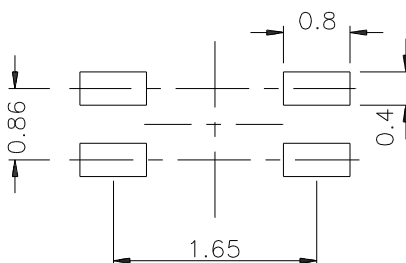


APTB1612SYKCGKC SMT Reflow Soldering Instructions

Number of reflow process shall be less than 2 times and cooling process to normal temperature is required between first and second soldering process.



Recommended Soldering Pattern (Units : mm)



Tape Specifications (Units : mm)

